group including the one or more retractable shelves, the one or more sliding assemblies, and the one or more load ports.

29. The semiconductor device fabrication line tool of claim 28, wherein the semiconductor device fabrication line tool comprises:

at least one of a semiconductor process tool, a metrology tool, or an inspection tool.

30. A method for buffering a semiconductor device fabrication line tool, comprising:

supporting one or more sealable containers on one or more retractable shelves;

transporting at least one of the one or more sealable containers to one or more load ports, wherein at least one of the one or more retractable shelves retracts to provide clearance for the one or more sealable containers;

transporting the at least one of the one or more sealable containers to at least one of the one or more retractable shelves.

31. A semiconductor device fabrication line tool, comprising:

one or more load ports, the one or more load ports configured to receive sealable containers; and

a buffer sub-system operatable in an active mode or a passive mode, comprising:

one or more retractable shelves, wherein at least one retractable shelf of the one or more retractable shelves is positionable above a load port of the one or more load ports, wherein the at least one retractable shelf is configured to engage in the retracted position when in the passive mode to provide clearance for transfer of sealable containers between an overhead delivery device and the load port, wherein the at least one retractable shelf is configured to engage in the extended position when in the active mode for transfer of the sealable containers with the overhead deliver device;

one or more sliding assemblies positioned above the one or more load ports, wherein the one or more sliding assemblies are configured to transport the sealable containers to one or more positions beneath the one or more retractable shelves when in the active mode; and

one or more lifting assemblies, wherein the one or more lifting assemblies are configured to transport the sealable containers between any two of a group including the one or more retractable shelves, the one or more sliding assemblies, and the one or more load ports when in the active mode.

32. The semiconductor device fabrication line tool of claim 31, wherein the passive mode is a backup to the active mode.

33. The semiconductor device fabrication line tool of claim 31, wherein the buffer subsystem is configured to dynamically switch between the active mode and the passive mode.